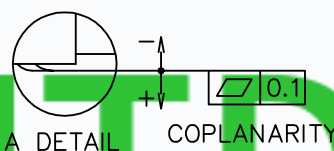
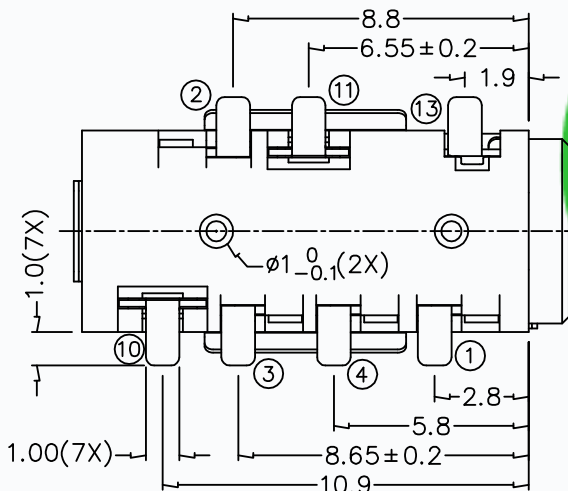
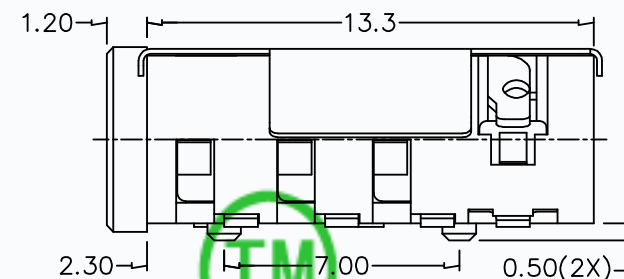
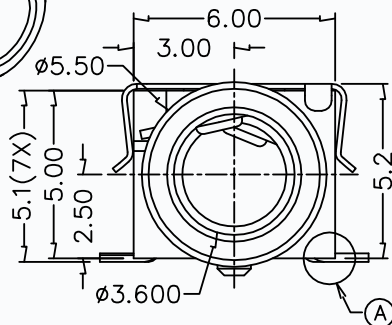
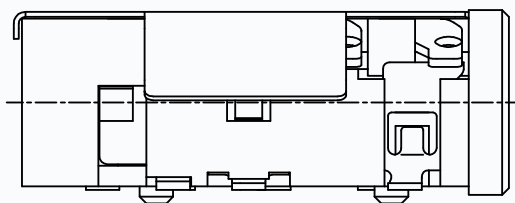
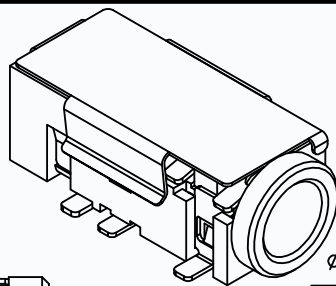
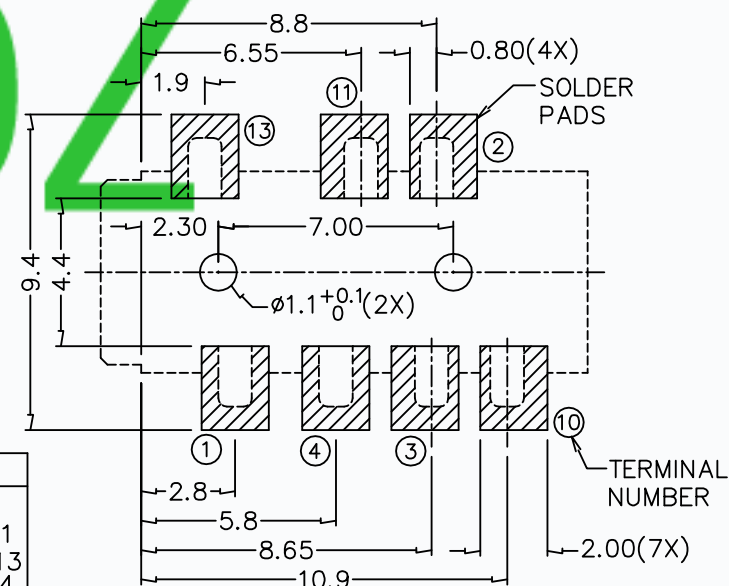
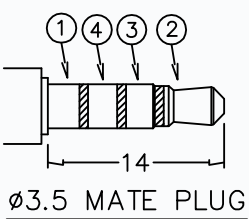


CAD FILE:



* MATERIAL

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 10 : BRASS
- TERMINAL 11 : BRASS
- TERMINAL 13 : COPPER ALLOY
- SHIELD : STAINLESS STEEL
- HOUSING : PA6T



MODEL NO.	T13-35917MS1	T13-35916AMS1	T13-35916BMS1	T13-35915MS1
SCHEMATIC				

RECOMMENDED SOLDER PAD LAYOUT

		<p>TOLERANCE UNLESS SPECIFIED</p> <p>WITHIN 1.5mm : ±0.1mm OVER 1.5mm : ±0.2mm</p>	<p>THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF DONGGUAN TIANDU ELECTRONICS CO.,LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF DONGGUAN TIANDU ELECTRONICS CO., LTD.</p>	<p>TITLE : 3.5mm SMD PHONE JACK</p>		<p>UNIT : mm</p>	<p>DRWG NO.: CMTDDZ-T13-3591MS1-00</p>		
				<p>MODEL: T13-3591MS1</p>		<p>SCALE: 3:1</p>		<p>DWN. ERIC</p>	<p>2013-6-17</p>
				<p>CMTDDZ 东莞市田都电子有限公司</p>		<p>CHK'D MAIKO</p>		<p>2013-6-17</p>	
<p>APPD.</p>	<p>DESCRIPTIONS OF REVISION</p>			<p>DONGGUAN TIANDU ELECTRONICS CO.,LTD.</p>		<p>APPD. Coco</p>		<p>2013-6-17</p>	